Celanese
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HOSTAFORM® C 9021

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Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988- POM-K, M-GNR, 03-002 POM copolymer Medium viscosity molding grade with high rigidity, hardness and toughness; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. Monomers and additives are listed in EU-Regulation (EU) 10/2011 FDA compliant according to 21 CFR 177.2470 UL-registration for all colours and a thickness more than 1.5 mm as UL 94 HB, temperature index UL 746 B electrical 110 °C, mechanical 90 °C. Burning rate ISO 3795 and FMVSS 302 < 75 mm/min for a thickness more than 1 mm. Ranges of applications: automotive engineering, precision engineering, electric and electronical industry, domestic appliances. FDA = Food and Drug Administration (USA) FMVSS = Federal Motor Vehicle Safety Standard (USA) UL = Underwriters Laboratories (USA)

Product information

Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

Rheological properties

Melt volume-flow rate	8	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	2.0	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.9[1]	%	ISO 294-4, 2577

[1]: @ 195°C

Typical mechanical properties

Tensile modulus	2850	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	64	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	30	%	ISO 527-1/-2
Flexural modulus	2700	MPa	ISO 178
Flexural strength	89	MPa	ISO 178
Flexural stress at 3.5%	72	MPa	ISO 178
Compressive stress at 1% strain	24	MPa	ISO 604
Tensile creep modulus, 1h	2500	MPa	ISO 899-1
Tensile creep modulus, 1000h	1300	MPa	ISO 899-1
Charpy impact strength, 23°C	220[P]	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	220	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	6.5	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	6	kJ/m^2	ISO 179/1eA
Ball indentation hardness, H 358/30	144	MPa	ISO 2039-1
Poisson's ratio	0.399		

[P]: Partial Break

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	104	°C	ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	160	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	110	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	110	E-6/K	ISO 11359-1/-2

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Thermal conductivity of melt	0.155	W/(m K)	ISO 22007-2

Flammability

Burning Behav. at 1.5mm nom. thickn.	HB	class	IEC 60695-11-10
Thickness tested	1.5	mm	IEC 60695-11-10
Burning Behav. at thickness h	HB	class	IEC 60695-11-10
Thickness tested	3	mm	IEC 60695-11-10
UL recognition	yes		UL 94

Electrical properties

Relative permittivity, 100Hz	4		IEC 62631-2-1
Relative permittivity, 1MHz	4		IEC 62631-2-1
Dissipation factor, 100Hz	20	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50	E-4	IEC 62631-2-1
Volume resistivity	1E12	Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	Ohm	IEC 62631-3-2
Electric strength	35	kV/mm	IEC 60243-1
Comparative tracking index	600		IEC 60112
Relative permittivity, printed circuits and boards, 2.5 GHz	3		IEC 61189-2-721
Relative permittivity, printed circuits and boards, 10 GHz	3.2		IEC 61189-2-721
Dissipation factor, printed circuits and boards, 2.5 GHz	466	E-4	IEC 61189-2-721
Dissipation factor, printed circuits and boards, 10 GHz	144	E-4	IEC 61189-2-721

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	1410	kg/m³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa
Ejection temperature	127	°C

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Characteristics

Processing	Injection Moulding, Film Extrusion, Extrusion, Sheet Extrusion, Other Extrusion, Blow Moulding
Delivery form	Pellets
Additives	Release agent

Additional information

Injection molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Film extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

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Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C
Annealing time 10 min/mm thickness

Other extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C
Annealing time 10 min/mm thickness

Sheet extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

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Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C
Annealing time 10 min/mm thickness

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

Storage

The product can then be stored in standard conditions until processed.

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
BAIC	Q-BJEV 01.59	
BMW	GS93016	
Bosch	N28 BN22-O010	Colors
Continental	SN 57914-7	
Continental	TST N 055 54.07	
Ford	WSK-M4D635-A2	Natural
Ford	WSK-M4D635-A2	Black 14
General Motors	GMW22P-POM-C2	Natural
Hyundai	MS237-14 Type A	

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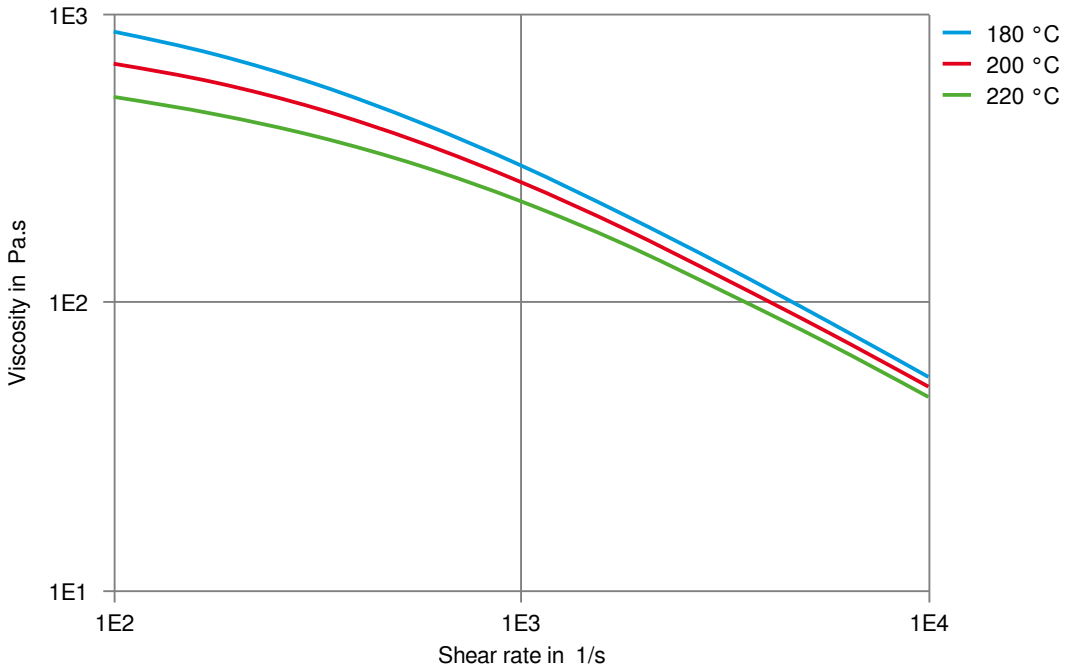
Mercedes-Benz		Door Lock Parts
Mercedes-Benz	DBL5405-06-POM-C	'Polyoxymethylene Copolymer'
Nissan	EP03-3	
Nissan	UB15b	
Stellantis	MS.502xx / POM-C.2400F.5C.MF	01994_14_00056, CPN 1532, CPN1586
Stellantis - Chrysler	MS.50095 / CPN-1532	Natural
Tesla	TM-1001-TMEP 3082	14 BLACK-IPH
VW Group	TL 526 36A	
VW Group	TL 526 36C	

Viscosity-shear rate



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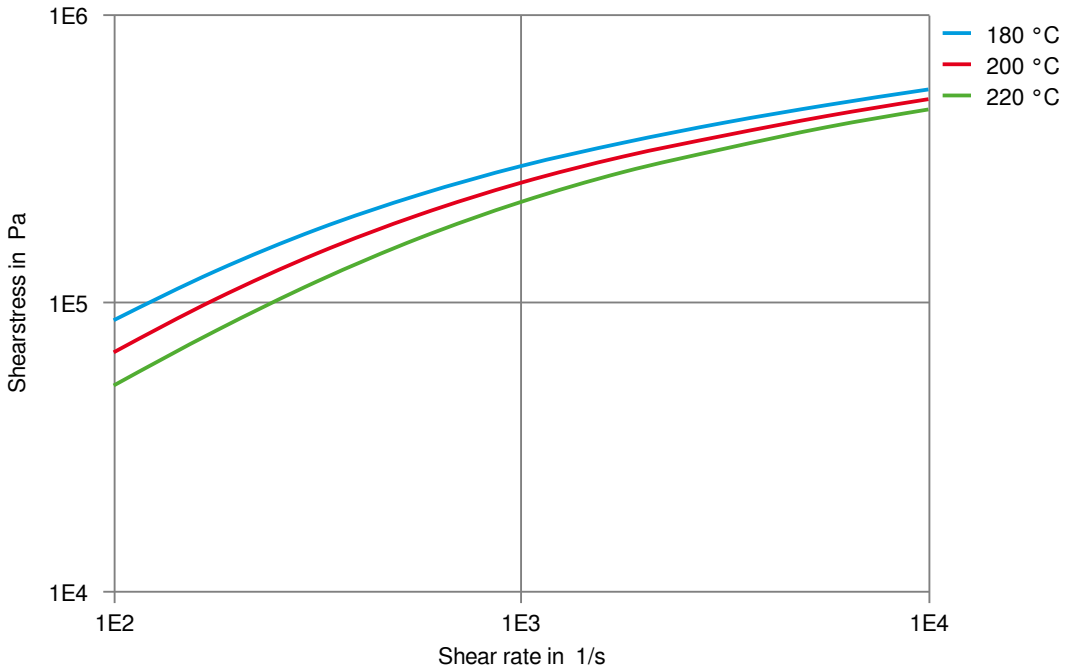
Shearstress-shear rate



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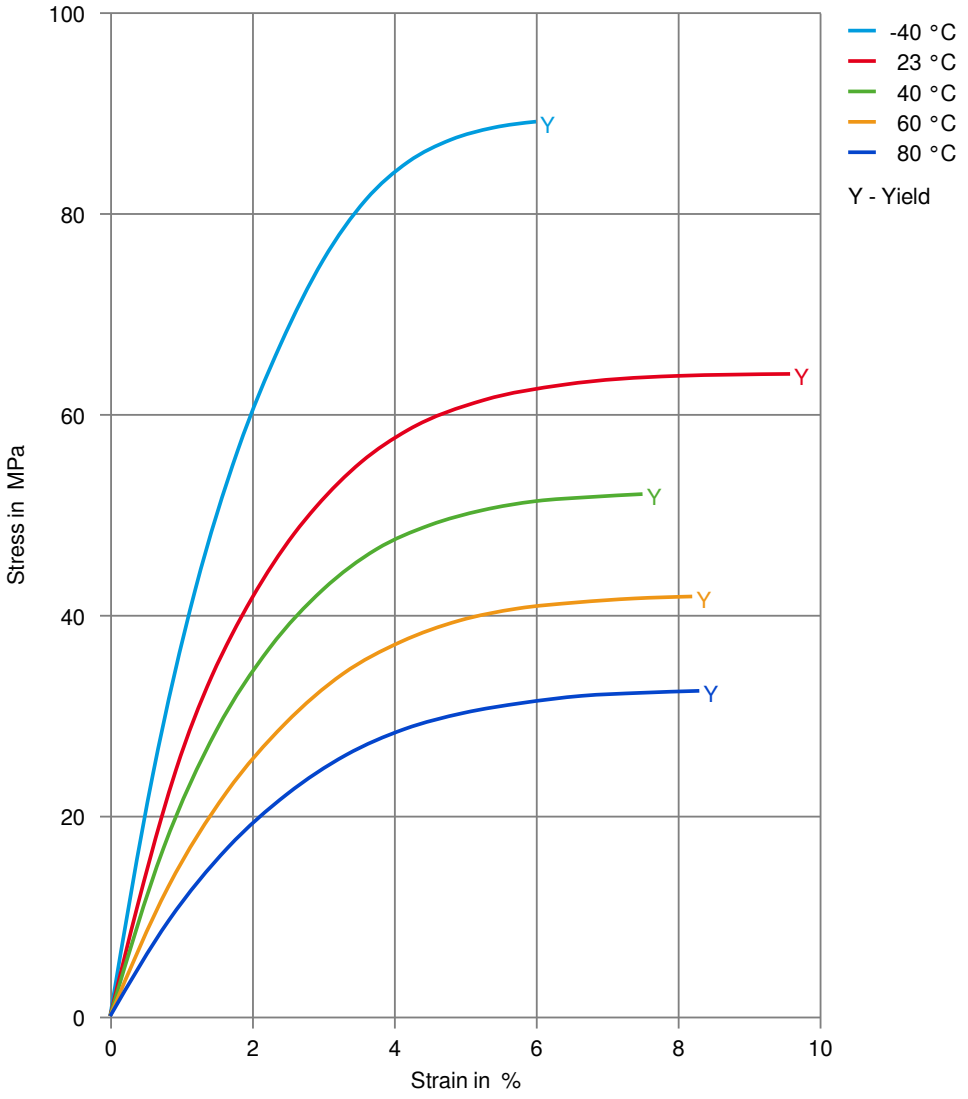
Stress-strain



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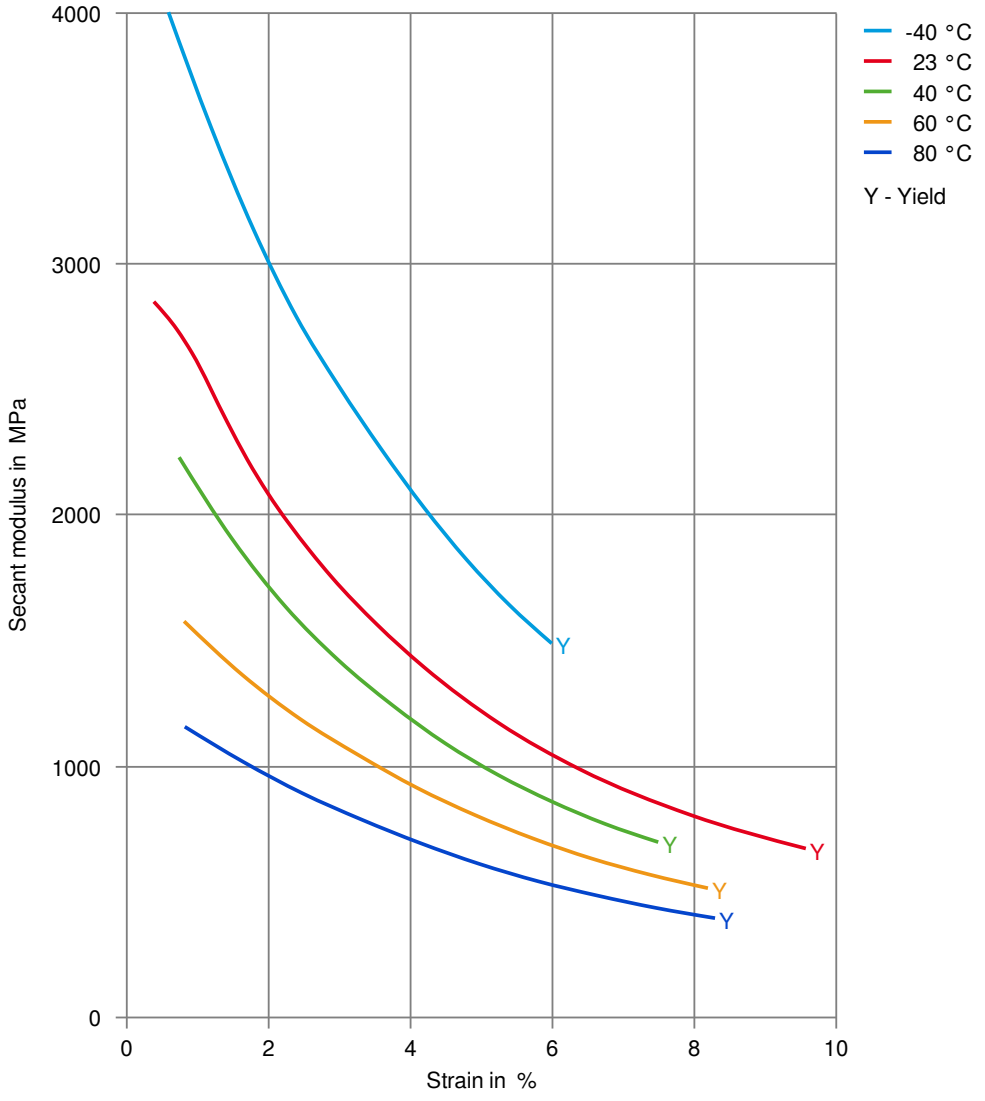
Secant modulus-strain



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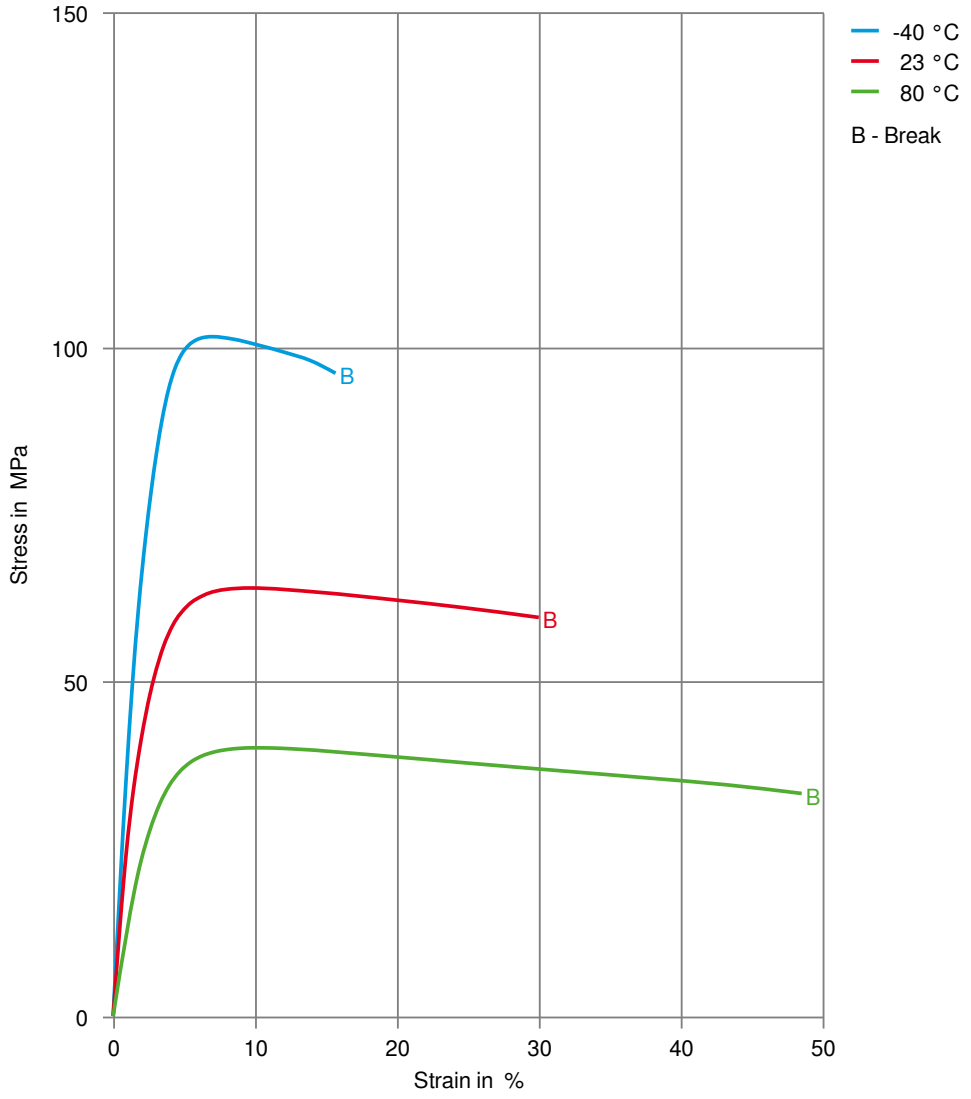
Stress-strain, 50mm/min



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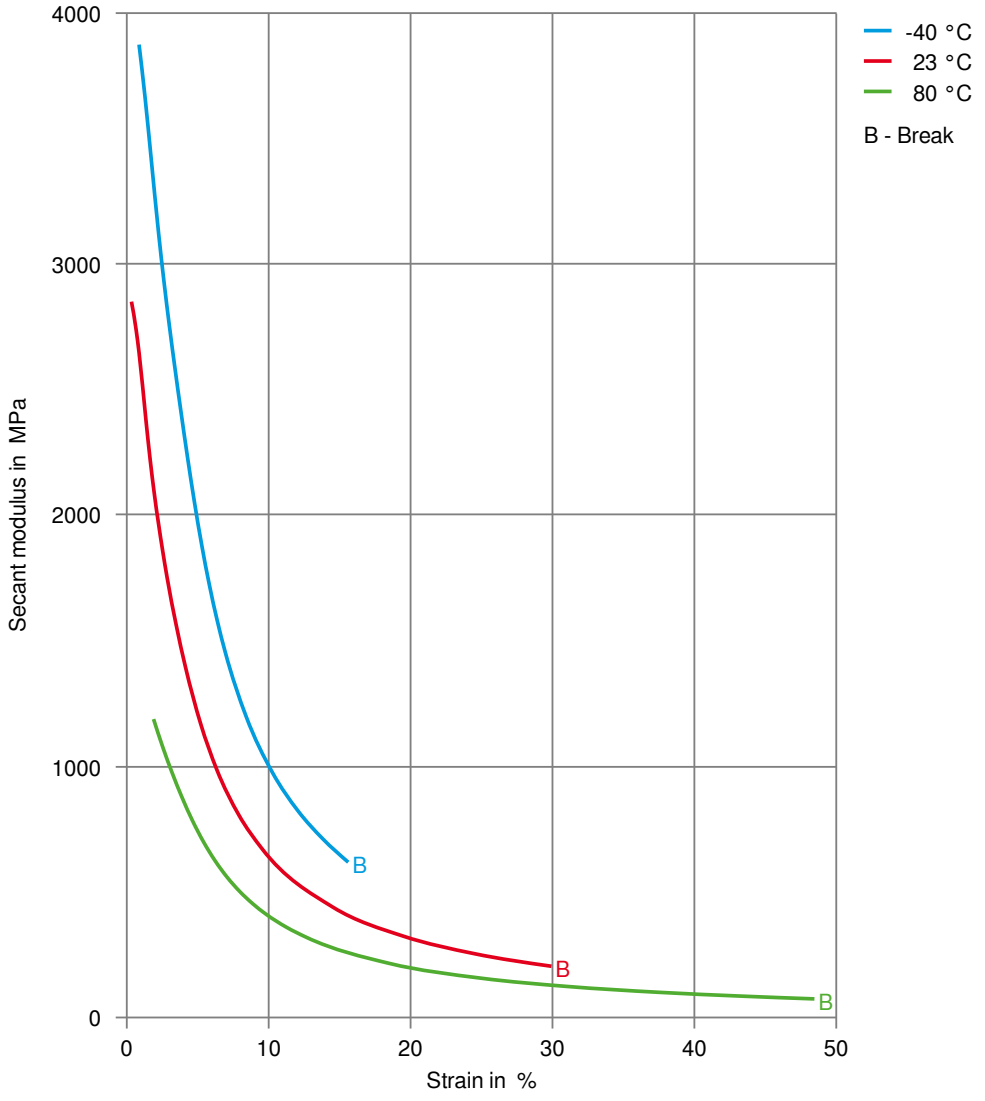
Secant modulus-strain, 50mm/min



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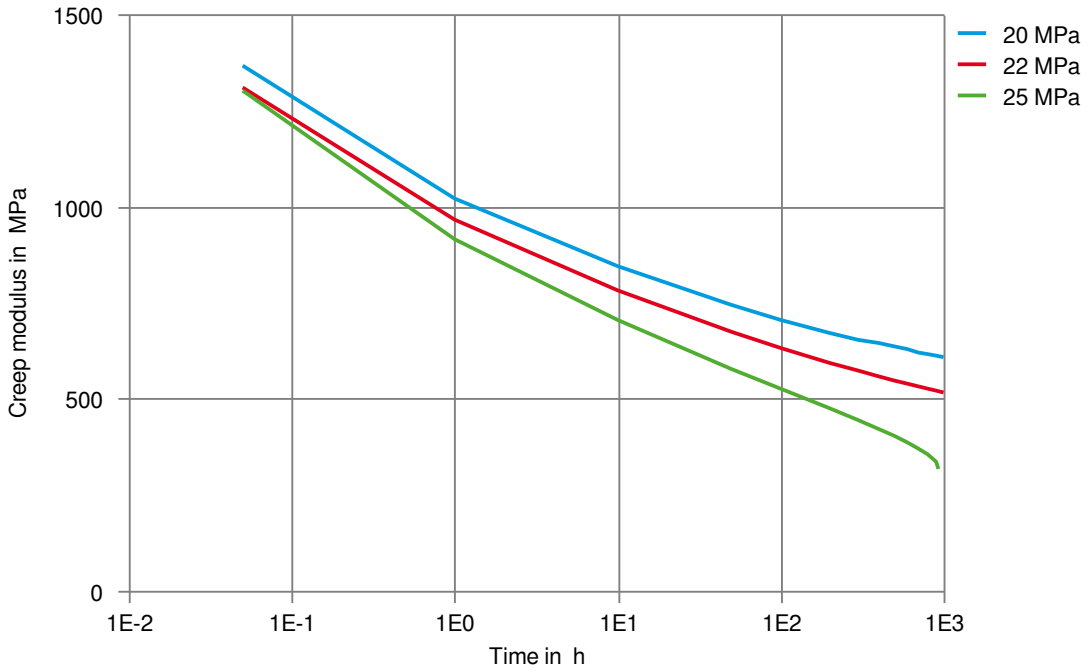
Creep modulus-time 60 °C



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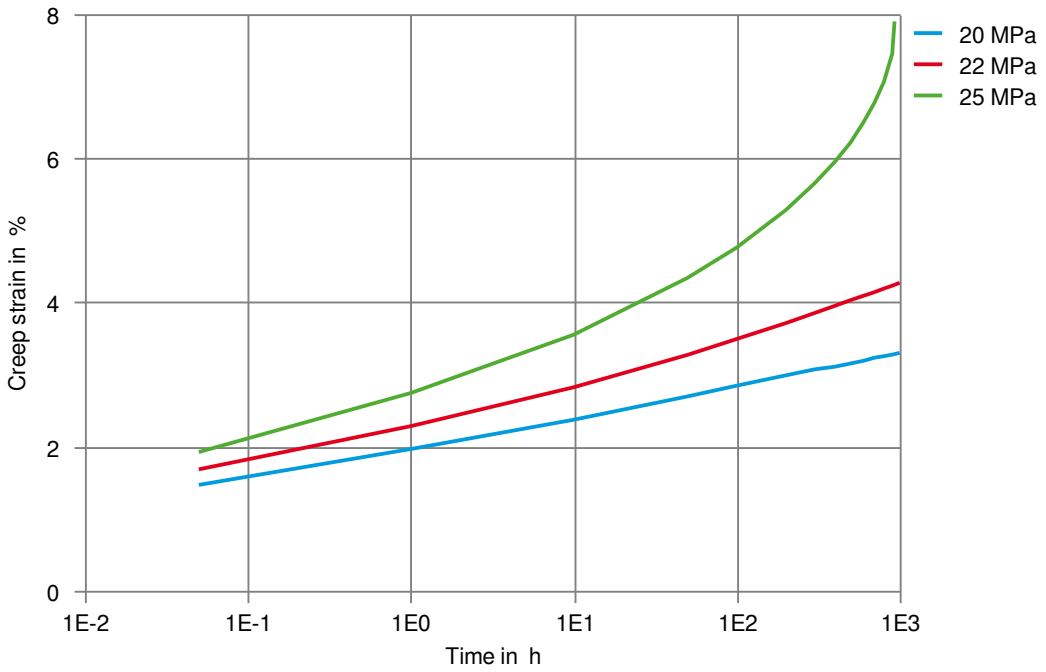
Creep strain-time 60 °C



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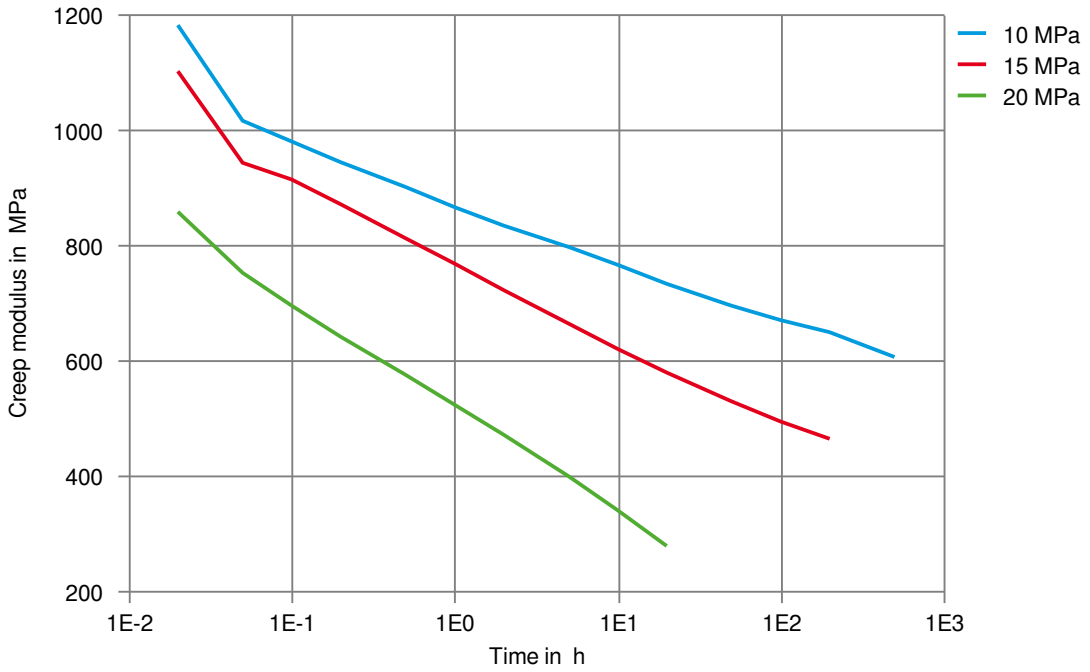
Creep modulus-time 90 °C



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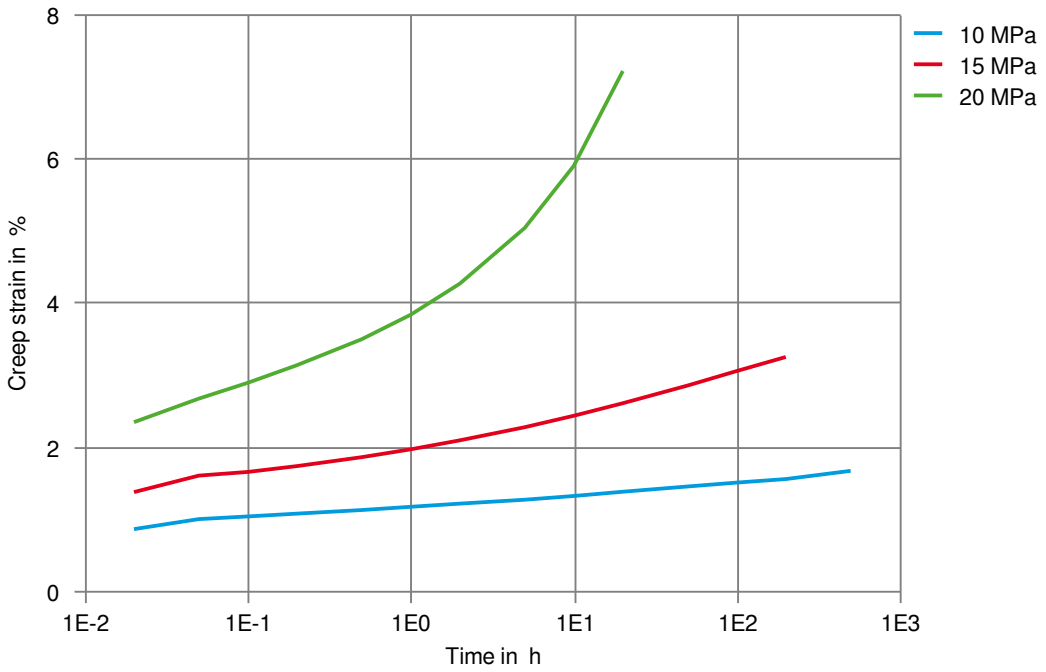
Creep strain-time 90 °C



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